



FF672 - PbSn SOLDER BALLS
 FFG672 - SnAgCu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	$\cancel{\text{---}}$	$\cancel{\text{---}}$	3.0	4
A ₁	0.40	0.50	0.60	
A ₂	$\cancel{\text{---}}$	$\cancel{\text{---}}$	2.40	
D/E	27.00 BASIC			
D ₁ /E ₁	25.00 REF			
e	1.00 BASIC			
phi b	0.50	0.60	0.70	
aaa	$\cancel{\text{---}}$	$\cancel{\text{---}}$	0.20	
ccc	$\cancel{\text{---}}$	$\cancel{\text{---}}$	0.35	
ddd	$\cancel{\text{---}}$	$\cancel{\text{---}}$	0.30	
eee	$\cancel{\text{---}}$	$\cancel{\text{---}}$	0.10	
M	26			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAL-1 (DEPOPULATED)
4. VIRTEX II-PRO: 'A' MAX IS 2.85mm, 'A2' MAX IS 2.25mm

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
10/30/02	1.0	Initial Xilinx release.
10/11/05	1.1	Added Pb-free specification.